

## Abstract

### Method for hermetic encapsulation of a component

- 5 For hermetic encapsulation of a component applied on a substrate (25) in a flip-chip construction, said component comprising a chip (1) with component structures (5), it is proposed to apply a material (35) onto the lower edge of the chip and regions of the substrate abutting the chip, and to apply thereon a first continuous metal layer (40) on the back side of the chip and on the material (35), as well as on
- 10 edge regions of the substrate abutting the material. For hermetic encapsulation, a second sealing metal layer (45) is subsequently applied (by means of a solvent-free process) at least on those regions of the first metal layer (40) that cover the material (35).

- 15 Fig. 4B.